

Product Description

Quick Details

| | | | |
|-------------------|----------------------------------------------------|-------------------|------------------------|
| Place of Origin | Guang dong, China (Mainland) | Brand Name | O-Leading |
| Base Material | FR-4,,Aluminum | Copper Thickness | 0.5oz-5oz |
| Min. Hole Size | 0.2mm | Min. Line Width | 0.2mm |
| Surface Finishing | immersion gold ,OSP,lead free HASL | Board Thickness | 0.1-5mm |
| applicable to | led,mobile phone,air conditioners,washing machines | character | Industrial Control pcb |
| certificates | ISO9001,UL,RoHS,SGS | Q/CTN | 10PCS-100PCS |
| weight | 0.01kg -5kg | MOQ | 10pcs |
| Model Number | power bank pcb assembly pcba manufacturer | Min. Line Spacing | 0.2mm |
| color | blue ,red ,green,black,yellow | price | \$0.1-\$10 |
| design type | client requirement | size | 0.01m3-10m3 |

Packaging & Delivery

| | |
|-------------------|--------------------------------------------------|
| Packaging Details | 16 years professional OEM pcb board manufacturer |
| Delivery Detail | 7-12days |

Product Description

16 years professional OEM pcb board manufacture

supplier [china Rigid-flexible pcb manufacturer](#), [Printed circuit board supplier](#), [Cheapest PCB makers china](#)

| item | 2014 | | 2015~2016 | | 2017~2018 | |
|-------------------------------------------|------------------------------------------------------------------------------------------------------------------------------------------------------------|--------|-----------|--------|-----------|--------|
| | Volume | Sample | Volume | Sample | Volume | Sample |
| Layer count | 32 | 42 | 38 | 44 | 42 | 48 |
| Min Line/space (µm) | 50/50 | 40/45 | 40/45 | 40/40 | 35/40 | 35/35 |
| Min drill hole diameter (mm) | 0.15 | 0.10 | 0.15 | 0.10 | 0.15 | 0.10 |
| Aspect ratio of PTH | 14:1 | 16:1 | 16:1 | 18:1 | 18:1 | 20:1 |
| N+C+N | 4+C+4 | 5+C+5 | 5+C+5 | 6+C+6 | 5+C+5 | 6+C+6 |
| Any layer interconnection | 5+2+5 | 6+2+6 | 5+2+5 | 6+2+6 | 5+2+5 | 6+2+6 |
| Plate filling via | YES | -- | YES | -- | YES | -- |
| Min. core thickness (exclude copper) (µm) | 50 | 40 | 40 | 30 | 40 | 30 |
| Min. Laser Drill diameter (µm) | 75 | 65 | 65 | 50 | 50 | 40 |
| Via on buried hole/stacked via | YES | -- | YES | -- | YES | -- |
| Material | FR4, Megtron, Nelco, Rogers, Heavy Copper, etc. | | | | | |
| Embedded capacitor PCB | YES | -- | YES | -- | YES | -- |
| Surface Process | Lead-free HASL, ENIG, OSP, Immersion silver, Immersion tin, Flash gold, Gold finger plating, Selective hard gold plating, Peelable solder mask, Carbon ink | | | | | |

